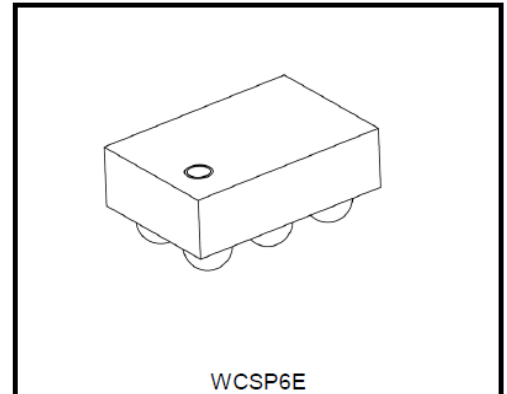


TOSHIBA CMOS Linear Integrated Circuit Silicon Monolithic

TCK401G, TCK402G

External FET Driver IC

The TCK401G and TCK402G are 28 V high input voltage External FET driver IC. It has wide input voltage operation. And this features a slew rate control driver with small package WCSP6E (0.8 mm x 1.2 mm, t: 0.55 mm). Also it can block reverse current if switch turned off by using external series FET. Thus this is suitable for power management selector such as Battery Charge application.

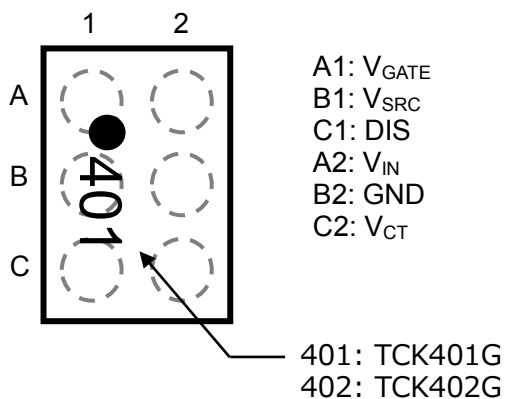


Weight: 1 mg(typ.)

Feature

- High maximum input voltage: $V_{IN\ max} = 40\ V$
- Wide input voltage operation: $V_{IN} = 2.7\ to\ 28\ V$
- Auto output discharge terminal
- Charge pump circuit
- Inrush current reducing circuit.
- Over Voltage lock out (Over 28 V)
- Under Voltage lock out (Under 2.7 V)
- Reverse Current Protection by External Back to Back MOSFET

Top marking (Top view)



Start of commercial production
2017-10

• Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Input voltage	V _{IN}	-0.3 to 40	V
Control voltage	V _{CT}	-0.3 to 6	V
Output GATE voltage	V _{GATE}	-0.3 to V _{IN_opr} + V _{GS}	V
SRC voltage	V _{SRC}	-0.3 to V _{GATE}	V
DIS voltage	V _{DIS}	-0.3 to 40	V
Power dissipation	P _D	800 (Note 1)	mW
Operating temperature range	T _{opr}	-40 to 85	°C
Junction temperature	T _j	150	°C
Storage temperature	T _{stg}	-55 to 150	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook (“Handling Precautions”/“Derating Concept and Methods”) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

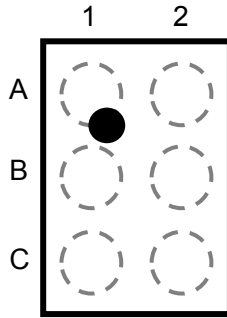
Note1: Rating at mounting on a board: FR4 board. (40 mm × 40 mm × 1.6 mm, Cu 4 layer)

• Recommended Operating Conditions

Characteristics	Symbol	Min.	Typ.	Max.	Unit
Input operation voltage	V _{IN_opr}	2.7	5.0	28	V
Capacitance	C _{IN}	0.1	1	—	μF
	C _{GATE}	—	2000	—	pF
CONTROL High-level input voltage	V _{IH}	1.6	—	—	V
CONTROL Low-level input voltage	V _{IL}	—	—	0.4	V

- Pin Assignment (Top view)

- WCSP6E

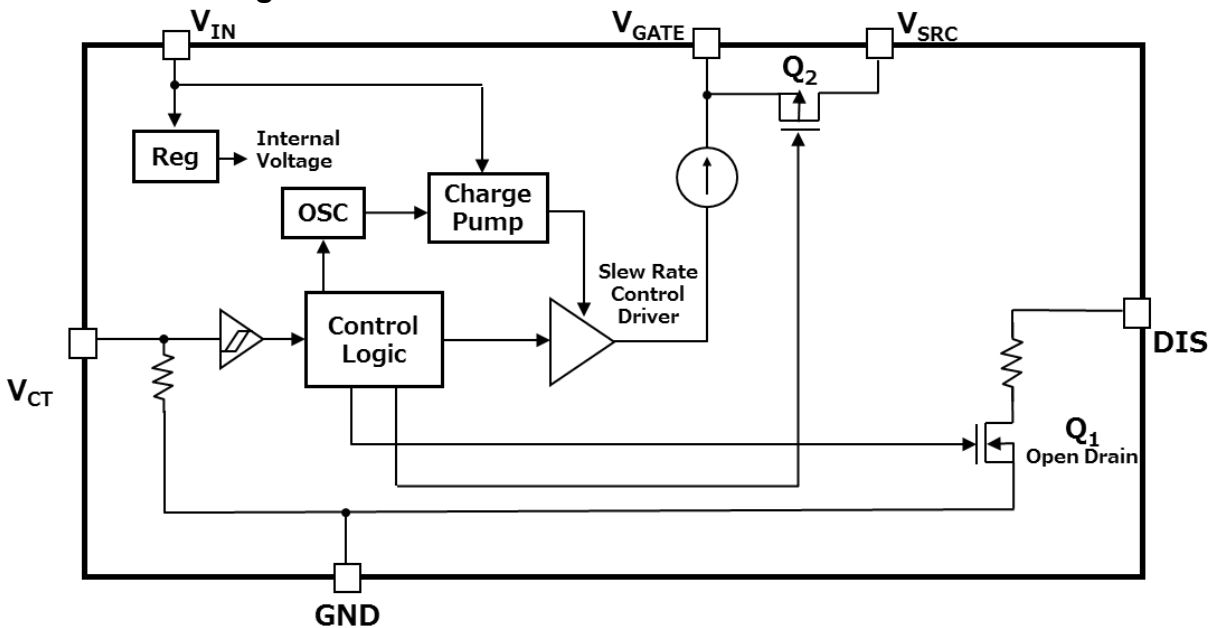


Pin #	Name	Pin #	Name
A1	V _{GATE}	A2	V _{IN}
B1	V _{SRC}	B2	GND
C1	DIS	C2	V _{CT}

- Product list

Part number	VCT function	VCT resistance
TCK401G	Active High	Pull down
TCK402G	Active Low	Pull down

- Block Diagram



TCK401G PIN Description

PIN	Name	Description
A1	V _{GATE}	Gate-Driver Output.
A2	V _{IN}	Supply voltage input.
B1	V _{SRC}	Recommend connecting V _{SRC} terminal to the common source connection of the external MOSFETs.
B2	GND	Ground
C1	DIS	Output Discharge terminal.
C2	V _{CT}	Mode control input terminal. When V _{CT} =High turn the external MOSFETs on, V _{CT} =Low, turn the external MOSFETs off.

- **TCK402G PIN Description**

PIN	Name	Description
A1	V _{GATE}	Gate-Driver Output.
A2	V _{IN}	Supply voltage input.
B1	V _{SRC}	Recommend connecting V _{SRC} terminal to the common source connection of the external MOSFETs.
B2	GND	Ground
C1	DIS	Output Discharge terminal.
C2	V _{CT}	Mode control input terminal. When V _{CT} =Low turn the external MOSFETs on, V _{CT} =High, turn the external MOSFETs off.

- **TCK401G Operation Status Table**

2.7V ≤ V_{IN} ≤ 28 V (Ta = -40 to 85°C)

V _{CT}	V _{GATE}	Discharge Q1	comment
High	ON (V _{IN} + V _{GS})	OFF	Driver ON mode
Open	OFF	ON	Driver OFF mode
Low			

- **TCK402G Operation Status Table**

2.7V ≤ V_{IN} ≤ 28 V (Ta = -40 to 85°C)

V _{CT}	V _{GATE}	Discharge Q1	comment
Low	ON (V _{IN} + V _{GS})	OFF	Driver ON mode
Open			
High	OFF	ON	Driver OFF mode

DC Characteristics (Ta = -40 to 85°C)

Characteristics	Symbol	Test Condition	Ta = 25°C			Ta = -40 to 85°C (Note 2)		Unit	
			Min.	Typ.	Max.	Min.	Max.		
Input quiescent current (ON state)	IQ(ON)	TCK401G	VCT: High, VIN = 5.0 V	—	121	—	—	222	μA
			VCT: High, VIN = 9.0 V	—	144	—	—	283	μA
			VCT: High, VIN = 12 V	—	159	—	—	294	μA
			VCT: High, VIN = 20 V	—	198	—	—	376	μA
		TCK402G	VCT: Low, VIN = 5.0 V	—	121	—	—	222	μA
			VCT: Low, VIN = 9.0 V	—	144	—	—	283	μA
			VCT: Low, VIN = 12 V	—	159	—	—	294	μA
			VCT: Low, VIN = 20 V	—	198	—	—	376	μA
Standby current (OFF state)	IQ(OFF)	TCK401G	VCT: Low, VIN = 5.0 V	—	3.0	—	—	4.8	μA
			VCT: Low, VIN = 9.0 V	—	5.9	—	—	8.2	μA
			VCT: Low, VIN = 12 V	—	8.0	—	—	11.2	μA
			VCT: Low, VIN = 20 V	—	13.8	—	—	19.2	μA
		TCK402G	VCT: High, VIN = 5.0 V	—	3.0	—	—	4.8	μA
			VCT: High, VIN = 9.0 V	—	5.9	—	—	8.2	μA
			VCT: High, VIN = 12 V	—	8.0	—	—	11.2	μA
			VCT: High, VIN = 20 V	—	13.8	—	—	19.2	μA
GATE Drive voltage(VGATE-VIN)	VGS	VIN = 3 V	—	4.0	—	2.8	5.1	V	
		VIN = 5 V	—	6.5	—	5.1	7.9	V	
		VIN = 9.0 V	—	6.5	—	5.1	7.9	V	
		12 V ≤ VIN ≤ 28 V	—	8.5	—	6.9	10.0	V	
Output current	IGATE(ON)	VIN = 5 V	—	38	—	—	—	μA	
DIS resistance	RDIS	—	—	21	—	—	—	kΩ	
Control pull down resistance	RCT	VCT= 5 V	—	600	—	—	—	kΩ	

Note 2: This parameter is warranted by design.

• **AC Characteristics (Ta = 25°C, VIN=5V, CGATE=2000pF)**

Characteristics	Symbol	Test Condition (Figure 1,2)	Min.	Typ.	Max.	Unit
VGATE ON time	tON	Initial startup time of VGATE (Note 3) voltage from 0V to VIN +1V	—	0.58	0.8	ms
VGATE OFF time	tOFF	VGATE =0.5V	—	16.6	—	μs
VGATE rise time	tr	VGATE rising from VIN +1V to VIN +3V	—	0.2	—	ms
VGATE fall time	tf	VGATE falling from VIN +3V to VIN +1V	—	1.5	—	μs

• **AC Characteristics (Ta = 25°C, VIN=9V, CGATE=2000pF)**

Characteristics	Symbol	Test Condition (Figure 1,2)	Min.	Typ.	Max.	Unit
VGATE ON time	tON	Initial startup time of VGATE (Note 3) voltage from 0V to VIN +1V	—	0.78	1.0	ms
VGATE OFF time	tOFF	VGATE=0.5V	—	19.7	—	μs
VGATE rise time	tr	VGATE rising from VIN +1V to VIN +4V	—	0.35	—	ms
VGATE fall time	tf	VGATE falling from VIN +4V to VIN +1V	—	1.6	—	μs

• **AC Characteristics (Ta = 25°C, VIN=12V, CGATE=2000pF)**

Characteristics	Symbol	Test Condition (Figure 1,2)	Min.	Typ.	Max.	Unit
VGATE ON time	tON	Initial startup time of VGATE (Note 3) voltage from 0V to VIN +1V	—	0.92	1.2	ms
VGATE OFF time	tOFF	VGATE=0.5V	—	21.3	—	μs
VGATE rise time	tr	VGATE rising from VIN +1V to VIN +5V	—	0.6	—	ms
VGATE fall time	tf	VGATE falling from VIN +5V to VIN +1V	—	1.7	—	μs

Note 3: This parameter is warranted by design.

Timing chart

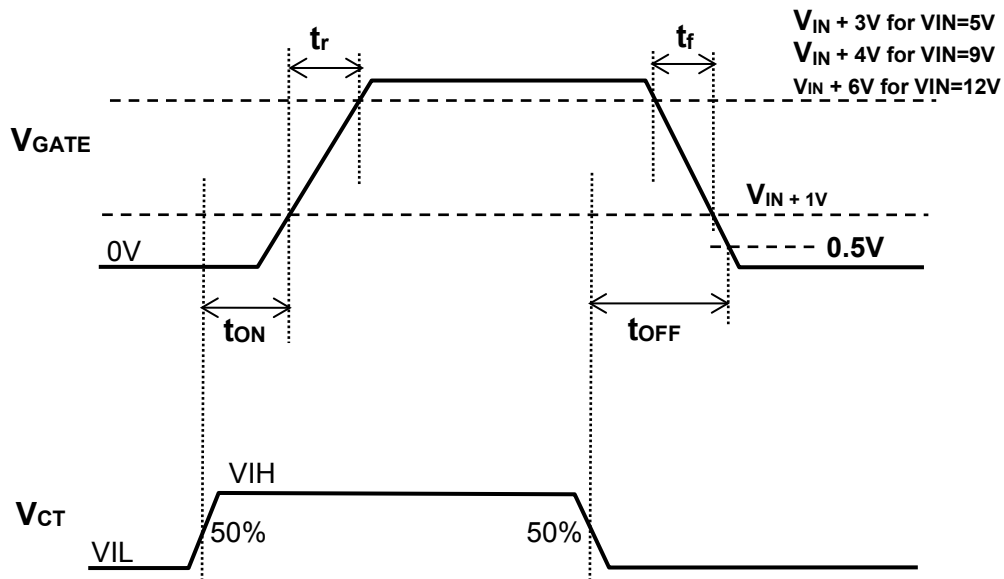


Fig.1 Active High (TCK401G)

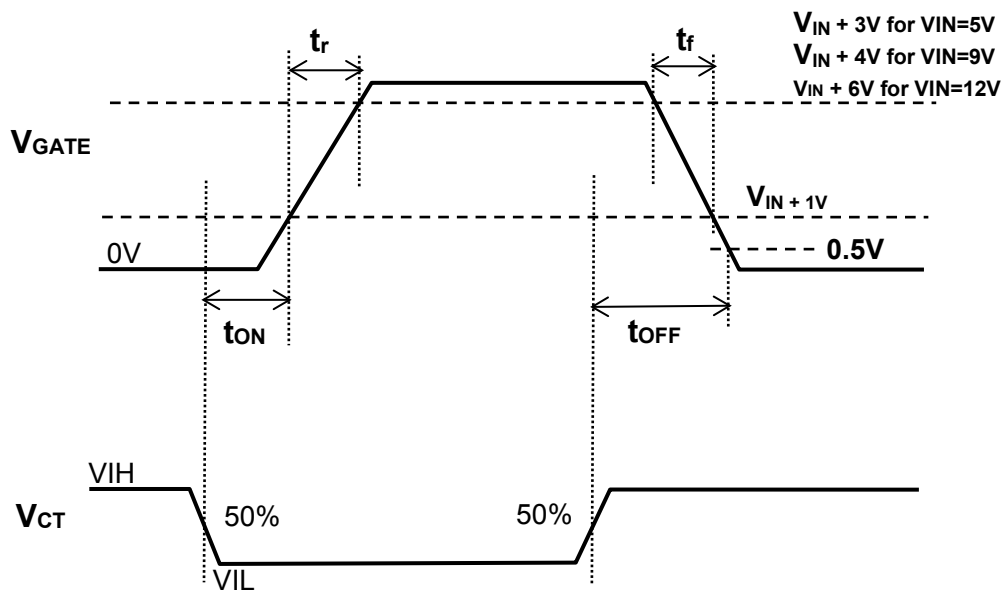
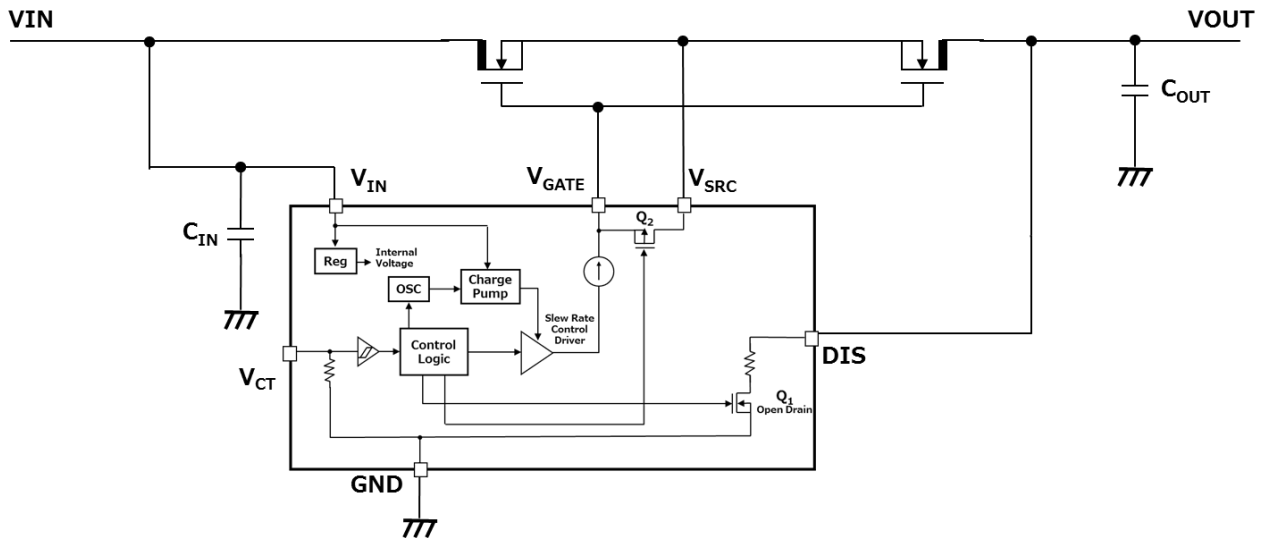


Fig.2 Active Low (TCK402G)

- Application Note

- Application circuit example



1) Input and Output capacitor

An input capacitor (C_{IN}) and an output capacitor (C_{OUT}) is recommended for the stable operation of TCK401G and TCK402G. And it is effective to reduce voltage overshoot or undershoot due to sharp changes in output current and also for improved stability of the power supply. When used, place C_{IN} and C_{OUT} more than $1.0\mu F$ as close to V_{IN} pin to improve stability of the power supply.

2) V_{CT} pin

V_{CT} pin for TCK401G and TCK402G is operated by the control voltage and Schmitt trigger. V_{CT} pin has a tolerant function such that it can be used even if the control voltage is higher than the input voltage.

3) SRC Pin

For Dual MOSFET Driver, V_{SRC} work for short between V_{GATE} and MOSFET source when Driver IC Turn off. If there are enough margins of V_{GS} of MOSFET, V_{SRC} terminal Open state is no problem.

For Single MOSFET Driver, if there are enough margins of V_{GS} of MOSFET, V_{SRC} pin Open state is no problem. If there are not enough margins, we recommend connecting V_{SRC} and V_{OUT} . If connect V_{SRC} and V_{OUT} , t_{OFF} time become longer because of C_{OUT} . Therefore, please consider enough margins for MOSFET selection.

4) DIS Pin

If need Discharge function when Driver IC Turn off, please connect DIS Pin to V_{OUT} . If no need, DIS Pin Open state is no problem.

5) Over Voltage Protection off time (t_{OVP})

Over Voltage (V_{IN} is over $V_{IN_opr\ max}$) Protection off time (t_{OVP}) is similar V_{GATE} OFF time (t_{OFF}).

Timing chart

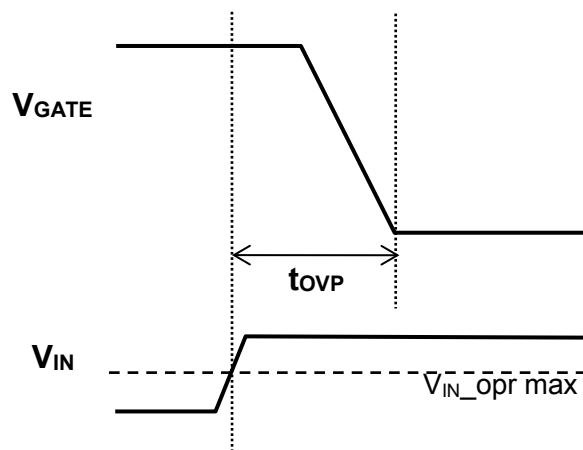
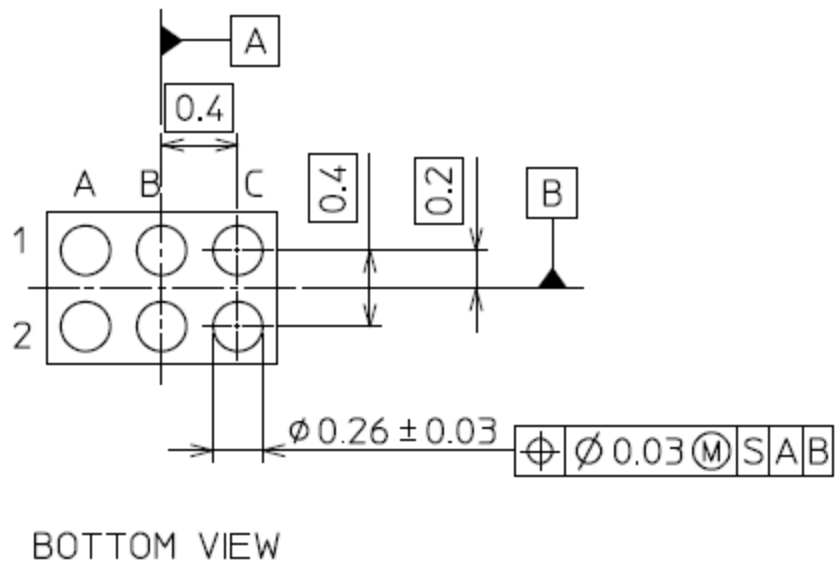
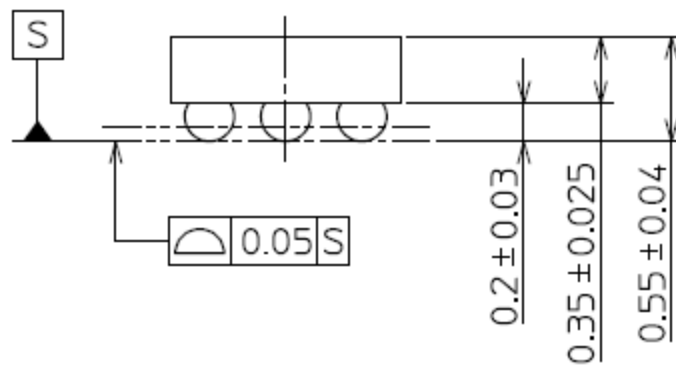
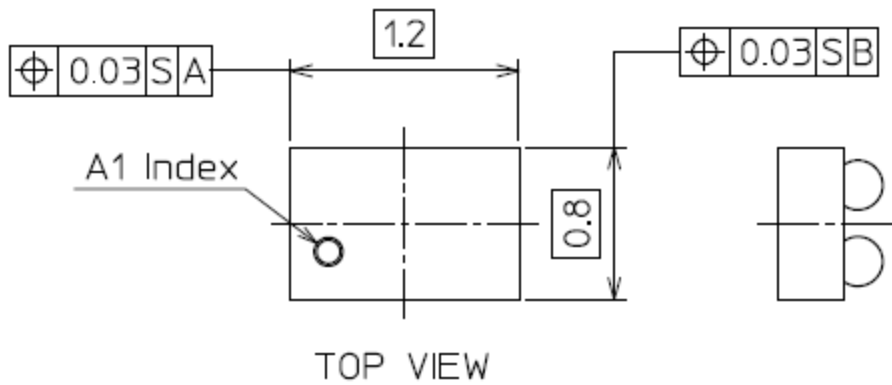


Fig.3 t_{OVP}

- Package dimension

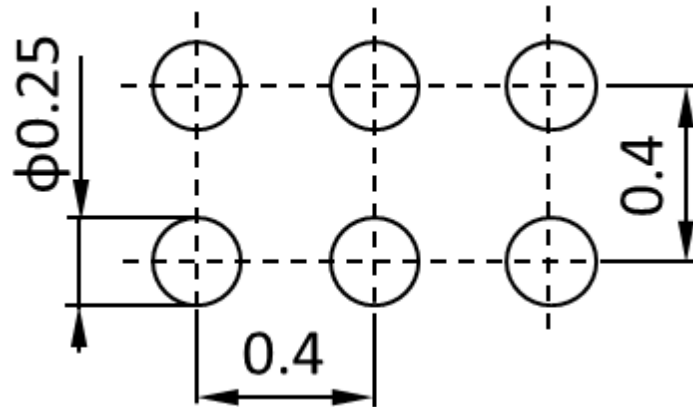
Unit: mm



Weight: 1 mg (typ.)

Land pattern dimensions (for reference only)

Unit: mm



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